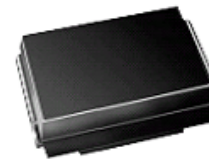


Major Ratings and Characteristics

$I_{F(AV)}$	1.0 A
V_{RRM}	20 V to 100 V
I_{FSM}	40 A
V_F	0.50V, 0.55 V, 0.70 V, 0.85V
$T_j \text{ max.}$	125°C



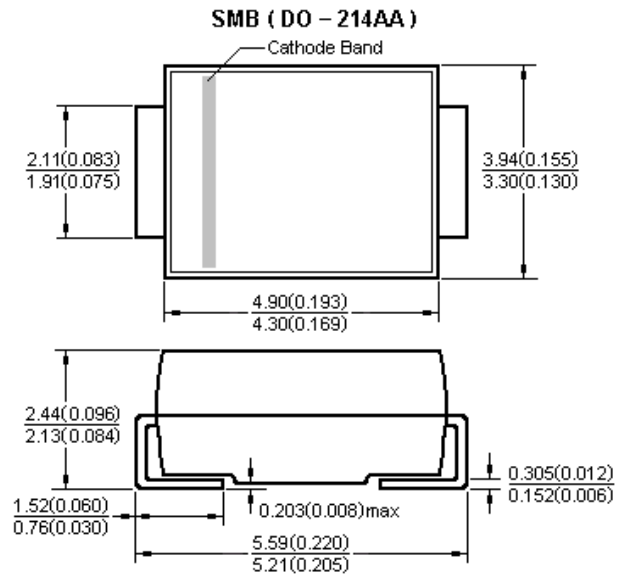
SMB (DO – 214AA)

Features

- Low profile package
- Ideal for automated placement
- Ultrafast reverse recovery time
- Low power losses, high efficiency
- Low forward voltage drop
- High surge capability
- High temperature soldering:
260°C/10 seconds at terminals
- Component in accordance to
RoHS 2002/95/1 and WEEE 2002/96/EC

Mechanical Date

- **Case:** JEDEC DO-214AA molded plastic body over passivated chip
- **Terminals:** Solder plated, solderable per J-STD-002B and JESD22-B102D
- **Polarity:** Laser band denotes cathode end



Dimensions in millimeters and (inches)

Maximum Ratings & Thermal Characteristics & Electrical Characteristics

($T_A = 25^\circ\text{C}$ unless otherwise noted)

	Symbol	SK12 SS12	SK13 SS13	SK14 SS14	SK15 SS15	SK16 SS16	SK18 SS18	SK110 SS110	UNIT
Maximum repetitive peak reverse voltage	V_{RRM}	20	30	40	50	60	80	100	V
Maximum RMS voltage	V_{RMS}	14	21	28	35	42	56	70	V
Maximum DC blocking voltage	V_{DC}	20	30	40	50	60	80	100	V
Maximum average forward rectified current	$I_{F(AV)}$	1							A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I_{FSM}	40							A
Maximum instantaneous forward voltage at 1.0A	V_F	0.50	0.55	0.70		0.85			V
Maximum DC reverse current at Rated DC blocking voltage	I_R	$T_A = 25^\circ\text{C}$			0.5				mA
		$T_A = 100^\circ\text{C}$			5				
Thermal resistance from junction to Lead	$R_{\theta JL}$	30							°C/W
Operating junction and storage temperature range	T_J, T_{STG}	- 65 to +125							°C

Characteristic Curves ($T_A=25\text{ }^\circ\text{C}$ unless otherwise noted)

